



60V SOT223 N-channel enhancement mode MOSFET

Product Summary

BV _{DSS}	R _{DS(on)} (Ω)	I _D (A)
201/	0.08 @ V _{GS} = 10V	5.3
60V	0.15 @ V _{GS} = 4.5V	2.8

Description and Applications

This MOSFET features a unique structure combining the benefits of low on-resistance and fast switching, making it ideal for high-efficiency power management applications.

- DC-DC Converters
- · Power Management Functions
- Disconnect Switches
- Motor Control

Features and Benefits

- Low On-Resistance
- · Fast Switching Speed
- Low Threshold
- · Low Gate Drive
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

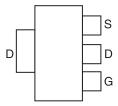
Mechanical Data

- Case: SOT223
- Case Material: Molded Plastic.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.112 grams (Approximate)

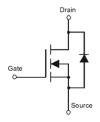




Top View



Pin Out - Top View



Equivalent Circuit

Ordering Information (Note 4)

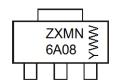
Part Number	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXMN6A08GTA	ZXMN6A08	7	12	1,000
ZXMN6A08GTC	ZXMN6A08	13	12	4.000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information

SOT223



ZXMN6A08 =Product Type Marking Code YWW = Date Code Marking Y or Y= Last Digit of Year (ex: 5 = 2015) WW or WW = Week Code (01 - 53)



Absolute Maximum Ratings

Characteristic		Symbol	Value	Unit
Drain-Source Voltage		V _{DSS}	60	V
Gate-Source Voltage		V _{GSS}	±20	V
	T _A = +25 °C (Note 6)		5.3	А
Continuous Drain Current V _{GS} = 10V	T _A = +70 °C (Note 6)	I _D	4.2	А
	T _A = +25 °C (Note 5)		3.8	А
Pulsed Drain Current (Note 7)		I _{DM}	20	А
Continuous Source Current (body diode)(Note 6)		I _S	2.1	А
Pulsed Source Current (body diode)(Note 7)		I _{SM}	20	А
Power Dissipation at T _A = +25 °C (Note 5) Linear Derating Factor		P _D	2 16	W mW/℃
Power Dissipation at $T_A = +25$ °C (Note 6) Linear Derating Factor		P _D	3.9 31	W mW/℃
Linear Derating Factor		T _J , T _{STG}	-55 to +150	∞

Thermal Characteristics (@TA = +25 °C, unless otherwise specified.)

Characteristic	Symbol	Value	Units
Junction to Ambient (Note 5)	$R_{\theta JA}$	62.5	°C/W
Junction to Ambient (Note 6)	$R_{\theta JA}$	32	°C/W

Electrical Characteristics (@T_A = +25 °C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage	BV _{DSS}	60	-	_	V	V _{GS} = 0V, I _D =250μA	
Zero Gate Voltage Drain Current	I _{DSS}	_	_	0.5	μΑ	V _{DS} = 60V, V _{GS} = 0V	
Gate-Source Leakage	I _{GSS}	-	-	100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS							
Gate Threshold Voltage	V _{GS(th)}	1	_	-	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$	
Static Drain-Source On-State Resistance (Note 8)		_	ı	0.08	Ω	$V_{GS} = 10V, I_D = 4.8A$	
Static Drain-Source On-State nesistance (Note 8)	R _{DS} (ON)	_	-	0.15	Ω	$V_{GS} = 4.5V, I_D = 4.2A$	
Forward Transconductance (Notes 8 &10)	g _{fs}	_	6.6	ı	S	$V_{DS} = 15V, I_{D} = 4.8A$	
DYNAMIC CHARACTERISTICS (Note 10)							
Input Capacitance	C _{iss}	_	459	_	pF		
Output Capacitance	Coss	-	44.2	_	pF	$V_{DS} = 40V, V_{GS} = 0V,$ - f = 1MHz	
Reverse Transfer Capacitance	C _{rss}	-	24.1	_	pF	=	
Turn-On Delay Time (Note 9)	t _{D(on)}	_	2.6	_	ns		
Turn-On Rise Time (Note 9)	t _r	_	2.1	_	ns	V _{DD} = 30V, I _D =1.5A	
Turn-Off Delay Time (Note 9)	t _{D(off)}	_	12.3	_	ns	$RG \cong 6.0\Omega, V_{GS}=10V$	
Turn-Off Fall Time (Note 9)	t _f	-	4.6	_	ns		
Gate Charge (Note 9)	Qg	-	4.0	1	nC	V _{DS} = 30V, V _{GS} = 5V I _D = 1.4A	
Total Gate Charge (Note 9)	Qg	-	5.8	_	nC	V 201/ 1/2 101/	
Gate-Source Charge (Note 9)	Qgs	_	1.4	_	nC	$V_{DS} = 30V, V_{GS} = 10V$	
Gate Drain Charge (Note 9)	Qgd	_	1.9	_	nC	I _D = 1.4A	
SOURCE-DRAIN DIODE							
Diode Forward Voltage (Note 8)	V _{SD}	-	0.88	1.2	V	Tj=+25°C, I _S = 4A, V _{GS} =0V	
Reverse Recovery Time (Note 10)	trr	_	19.2	_	ns	Tj=+25℃, I _S = 1.4A,	
Reverse Recovery Charge (Note 10)	Qrr	-	30.3	_	nC	di/dt=100A/μs	

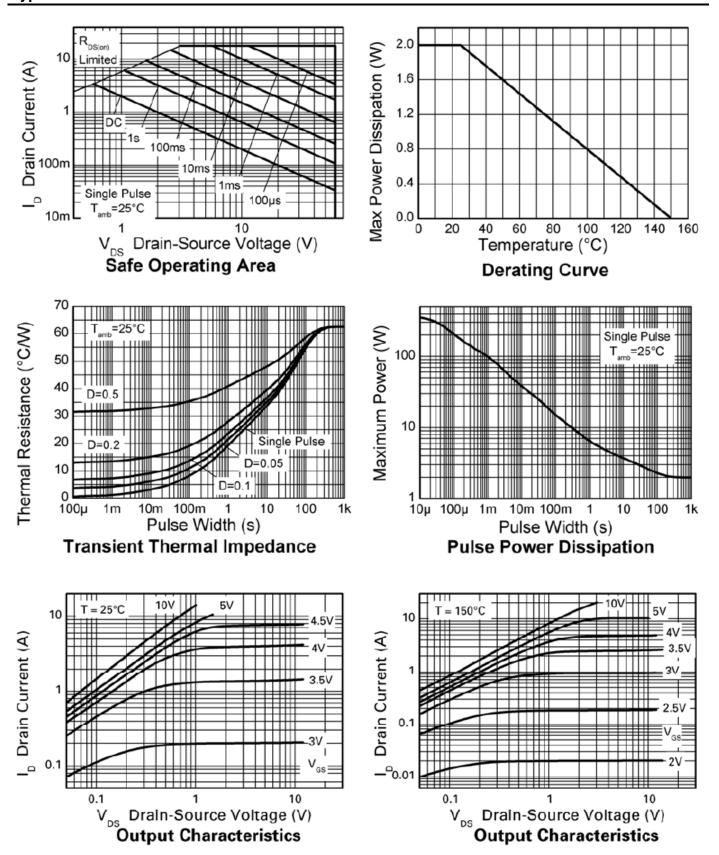
5. For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.
6. For a device surface mounted on FR4 PCB measured at t <= 10 sec.
7. Repetitive rating - 25mm x 25mm FR4 PCB, D=0.02, pulse width 300_s - pulse width limited by maximum junction temperature.
8. Measured under pulsed conditions. Pulse width <= 300_s; duty cycle <=2%. Notes:

- 9. Switching characteristics are independent of operating junction temperature.
- 10. For design aid only, not subject to production testing.

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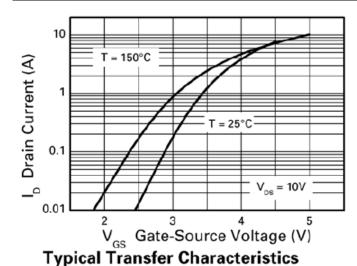


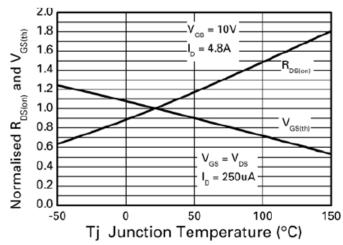
Typical Characteristics



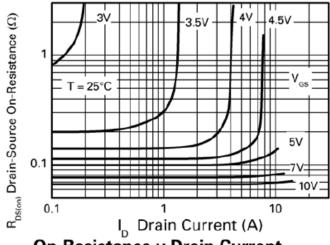


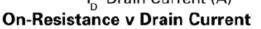
Typical Characteristics (continued)

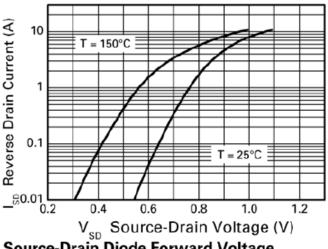




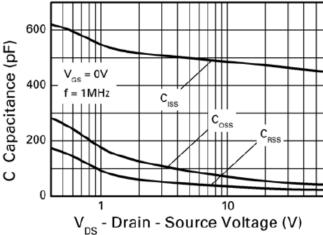
Normalised Curves v Temperature



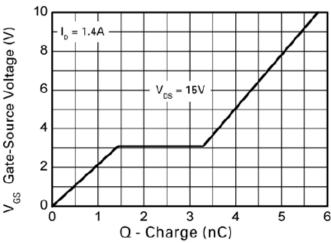




Source-Drain Diode Forward Voltage



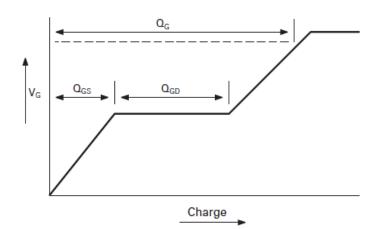
Capacitance v Drain-Source Voltage



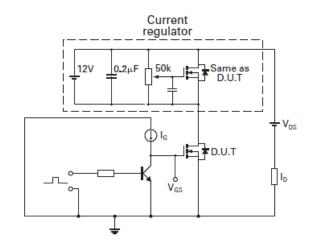
Gate-Source Voltage v Gate Charge



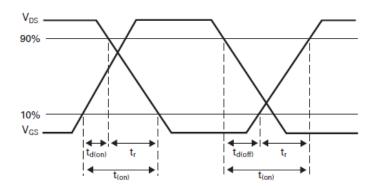
Test Circuits



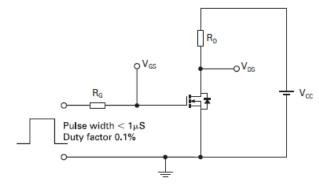
Basic gate charge waveform



Gate charge test circuit



Switching time waveforms

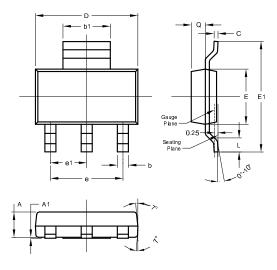


Switching time test circuit



Package Outline Dimensions

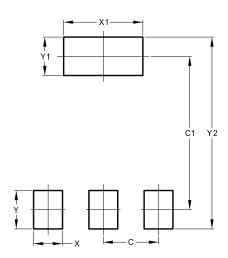
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



SOT223					
Dim	Min	Max	Тур		
Α	1.55	1.65	1.60		
A 1	0.010	0.15	0.05		
b	0.60	0.80	0.70		
b1	2.90	3.10	3.00		
С	0.20	0.30	0.25		
D	6.45	6.55	6.50		
Е	3.45	3.55	3.50		
E1	6.90	7.10	7.00		
е	-	-	4.60		
e1	-	-	2.30		
L	0.85	1.05	0.95		
Q	0.84	0.94	0.89		
All Dimensions in mm					

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	2.30
C1	6.40
Х	1.20
X1	3.30
Υ	1.60
Y1	1.60
Y2	8.00



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